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CLIPPEDIMAGE= JP360161973A

PAT-NO: JP360161973A

DOCUMENT-IDENTIFIER: JP 60161973 A

TITLE: PREPARATION OF NOVEL EPOXY RESIN

PUBN-DATE: August 23, 1985

INVENTOR-INFORMATION:

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INT-CL (IPC): C07D303/14; C08G059/20 ; C08G065/32 ;

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ABSTRACT:

NEW MATERIAL: An epoxy compound expressed by formula I
[R<SB>1</SB> is organic

compound residue having 1 active H atoms; n<SB>1</SB>,
n<SB>2</SB>...n<SB>1</SB> are integers 0∼100, and the
sum thereof is

1∼100; 1 is an integer 1∼100; B is expressed by
formula II[X is

expressed by formula III, IV or V (R<SB>2</SB> is H, alkyl,
alkylcarbonyl or

arylcarbonyl), and contains one or more groups expressed
by formula III in the
resin expressed by formula I].

EXAMPLE: The compound expressed by formula VI (n is 2 on
the average).

USE: An alicyclic epoxy resin compound, having rapidly
curable terminal epoxy
groups and improved heat resistance and electrical
characteristics without
containing chlorine, and applicable to preparation of
large-scale integrated
circuits (LSI) sealing materials, sealants for light
emitting diodes (LED) and
semiconductors and coating materials, etc.

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PREPARATION: An unsaturated compound expressed by formula VII (A is cyclohexane skeleton having vinyl group of formula VIII) is reacted with an epoxidizing agent, e.g. peracetic acid, if necessary in a solvent at -70∼+200°C to give the aimed compound expressed by formula I .

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